1.6X0.8mm SMD CHIP LED LAMP

Part Number: KPC-1608SEC-E Hyper Red

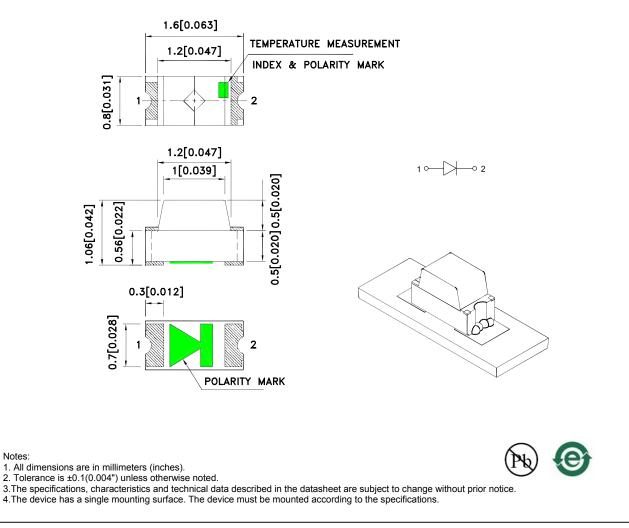
Features

- 1.6mmX0.8mm SMT LED, 1.06mm thickness.
- Low power consumption.
- · Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package: 3000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Hyper Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

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Selection Guide									
Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]				
			Min.	Тур.	201/2				
KPC-1608SEC-E	Hyper Red (AlGaInP) Wa	Water Clear	200	450	150°(H) 135°(V)				
			*55	*100					

Notes: 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	630		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Hyper Red	621		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	20		nm	I⊧=20mA
С	Capacitance	Hyper Red	25		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Hyper Red	2	2.5	V	I⊧=20mA
lr	Reverse Current	Hyper Red		10	uA	VR=5V

Notes:

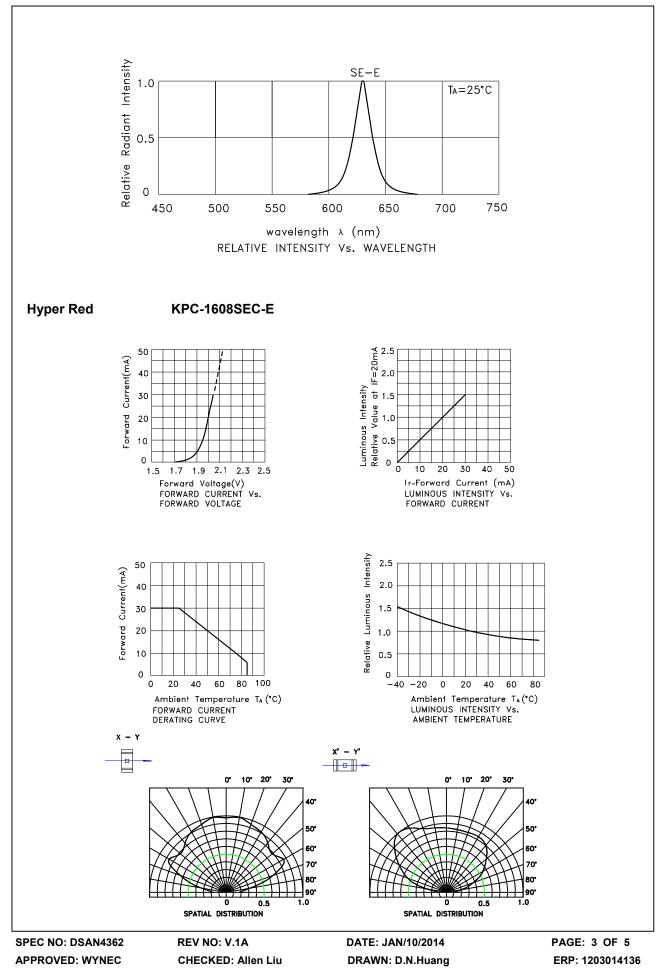
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	195	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

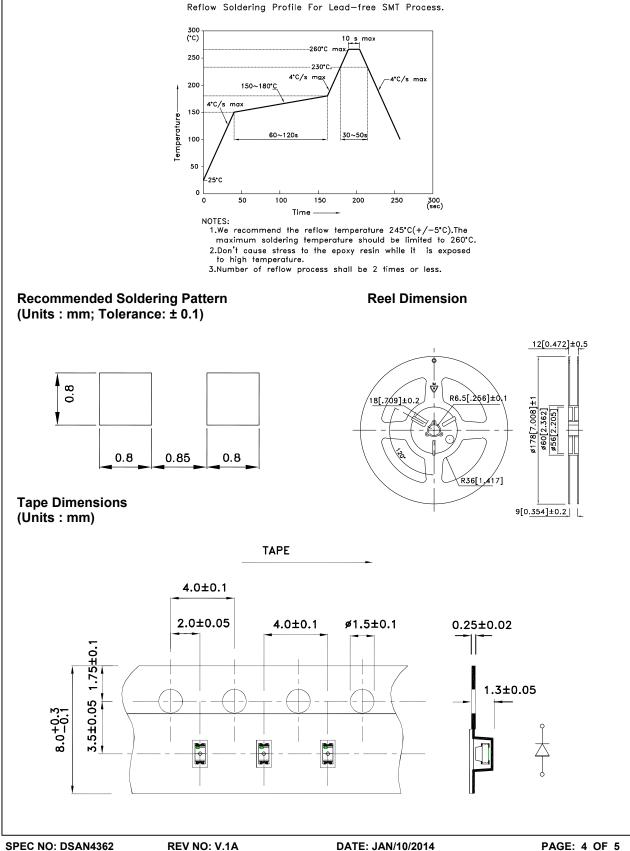
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



KPC-1608SEC-E

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

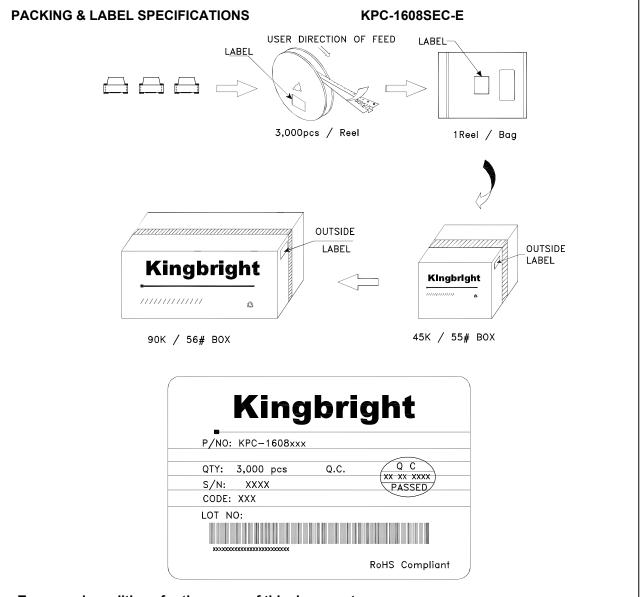
Reflow Soldering Profile For Lead-free SMT Process.



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